QFN32 5x5, 0.5P
CASE 485CE
ISSUE O

DATE 07 FEB 2012

SCALE 2:1

1 32

PIN ONE
REFERENCE

D

A
B

E

0.15 | C

0.15 | C

TOP VIEW

0.10 | C

0.08 | C

NOTE 4

SIDE VIEW

DETAIL B

(A3)

A

A1

C SEATING
PLANE

L

L

L1

DETAIL A
ALTERNATE
CONSTRUCTIONS

EXPOSED Cu   MOLD CMPD

DETAIL B
ALTERNATE
CONSTRUCTION

DETAIL A

D2

K

8

17

E2

32X L

1

32   25

24

32X b

e

e/2

0.10 Ⓜ | C | A-B | B
0.05 Ⓜ | C | NOTE 3

BOTTOM VIEW
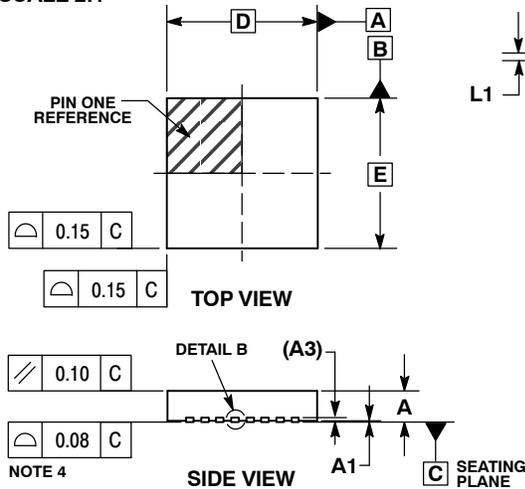
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20 REF	
b	0.20	0.30
D	5.00 BSC	
D2	3.40	3.60
E	5.00 BSC	
E2	3.40	3.60
e	0.50 BSC	
K	0.20	---
L	0.30	0.50
L1	---	0.15

**GENERIC
MARKING DIAGRAM***

1 ○

XXXXXXXX
XXXXXXXX
AWLYYWWG
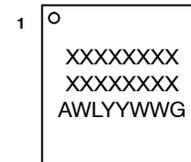
XXXXX = Specific Device Code
A   = Assembly Location
WL   = Wafer Lot
YY   = Year
WW   = Work Week
G   = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪ ", may or may not be present.
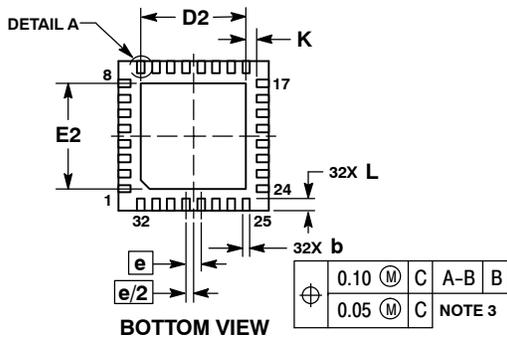
**RECOMMENDED
SOLDERING FOOTPRINT***

5.30

3.70

32X
0.62

3.70

5.30

0.50
PITCH

32X
0.30

DIMENSIONS: MILLIMETERS
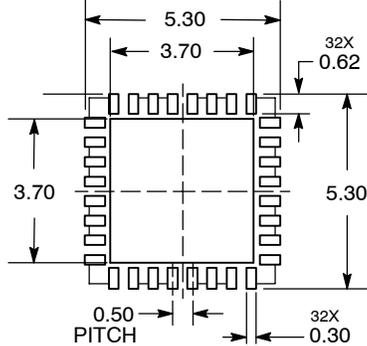
*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
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